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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	A/D 8x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/pic16c74a-20i-p">https://www.e-xfl.com/product-detail/microchip-technology/pic16c74a-20i-p</a>

# PIC16C7X

**TABLE 1-1: PIC16C7XX FAMILY OF DEVICES**

		PIC16C710	PIC16C71	PIC16C711	PIC16C715	PIC16C72	PIC16CR72 <sup>(1)</sup>
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20
	EPROM Program Memory (x14 words)	512	1K	1K	2K	2K	—
Memory	ROM Program Memory (14K words)	—	—	—	—	—	2K
	Data Memory (bytes)	36	36	68	128	128	128
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0	TMR0	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
	Capture/Compare/PWM Module(s)	—	—	—	—	1	1
	Serial Port(s) (SPI/I <sup>2</sup> C, USART)	—	—	—	—	SPI/I <sup>2</sup> C	SPI/I <sup>2</sup> C
	Parallel Slave Port	—	—	—	—	—	—
	A/D Converter (8-bit) Channels	4	4	4	4	5	5
Features	Interrupt Sources	4	4	4	4	8	8
	I/O Pins	13	13	13	13	22	22
	Voltage Range (Volts)	3.0-6.0	3.0-6.0	3.0-6.0	3.0-5.5	2.5-6.0	3.0-5.5
	In-Circuit Serial Programming	Yes	Yes	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	—	Yes	Yes	Yes	Yes
	Packages	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC	18-pin DIP, SOIC; 20-pin SSOP	18-pin DIP, SOIC; 20-pin SSOP	28-pin SDIP, SOIC, SSOP	28-pin SDIP, SOIC, SSOP

		PIC16C73A	PIC16C74A	PIC16C76	PIC16C77
Clock	Maximum Frequency of Operation (MHz)	20	20	20	20
	EPROM Program Memory (x14 words)	4K	4K	8K	8K
Memory	Data Memory (bytes)	192	192	368	368
	Timer Module(s)	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
Peripherals	Capture/Compare/PWM Module(s)	2	2	2	2
	Serial Port(s) (SPI/I <sup>2</sup> C, USART)	SPI/I <sup>2</sup> C, USART	SPI/I <sup>2</sup> C, USART	SPI/I <sup>2</sup> C, USART	SPI/I <sup>2</sup> C, USART
	Parallel Slave Port	—	Yes	—	Yes
Features	A/D Converter (8-bit) Channels	5	8	5	8
	Interrupt Sources	11	12	11	12
	I/O Pins	22	33	22	33
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0
	In-Circuit Serial Programming	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	Yes	Yes	Yes
	Packages	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C7XX Family devices use serial programming with clock pin RB6 and data pin RB7.

Note 1: Please contact your local Microchip sales office for availability of these devices.

# PIC16C7X

**TABLE 4-3: PIC16C76/77 SPECIAL FUNCTION REGISTER SUMMARY (Cont.'d)**

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets (2)	
<b>Bank 1</b>												
80h <sup>(4)</sup>	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	0000 0000	
81h	OPTION	RBP $\bar{U}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111	
82h <sup>(4)</sup>	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	0000 0000	
83h <sup>(4)</sup>	STATUS	IRP	RP1	RP0	T $\bar{O}$	PD	Z	DC	C	0001 1xxx	000q quuu	
84h <sup>(4)</sup>	FSR	Indirect data memory address pointer								xxxx xxxx	uuuu uuuu	
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	--11 1111	
86h	TRISB	PORTB Data Direction Register								1111 1111	1111 1111	
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111	
88h <sup>(5)</sup>	TRISD	PORTD Data Direction Register								1111 1111	1111 1111	
89h <sup>(5)</sup>	TRISE	IBF	OBF	IBOV	PSPMODE	—	PORTE Data Direction Bits				0000 -111	0000 -111
8Ah <sup>(1,4)</sup>	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter						---0 0000	---0 0000
8Bh <sup>(4)</sup>	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u	
8Ch	PIE1	PSPIE <sup>(3)</sup>	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000	
8Dh	PIE2	—	—	—	—	—	—	—	CCP2IE	---- --0	---- --0	
8Eh	PCON	—	—	—	—	—	—	POR	BOR	---- --qq	---- --uu	
8Fh	—	Unimplemented								—	—	
90h	—	Unimplemented								—	—	
91h	—	Unimplemented								—	—	
92h	PR2	Timer2 Period Register								1111 1111	1111 1111	
93h	SSPADD	Synchronous Serial Port (I <sup>2</sup> C mode) Address Register								0000 0000	0000 0000	
94h	SSPSTAT	SMP	CKE	D/ $\bar{A}$	P	S	R/ $\bar{W}$	UA	BF	0000 0000	0000 0000	
95h	—	Unimplemented								—	—	
96h	—	Unimplemented								—	—	
97h	—	Unimplemented								—	—	
98h	TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010	
99h	SPBRG	Baud Rate Generator Register								0000 0000	0000 0000	
9Ah	—	Unimplemented								—	—	
9Bh	—	Unimplemented								—	—	
9Ch	—	Unimplemented								—	—	
9Dh	—	Unimplemented								—	—	
9Eh	—	Unimplemented								—	—	
9Fh	ADCON1	—	—	—	—	—	PCFG2	PCFG1	PCFG0	---- -000	---- -000	

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented read as '0'.

Shaded locations are unimplemented, read as '0'.

Note 1: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<12:8> whose contents are transferred to the upper byte of the program counter.

2: Other (non power-up) resets include external reset through MCLR and Watchdog Timer Reset.

3: Bits PSPIE and PSPIF are reserved on the PIC16C76, always maintain these bits clear.

4: These registers can be addressed from any bank.

5: PORTD and PORTE are not physically implemented on the PIC16C76, read as '0'.

## 4.2.2.2 OPTION REGISTER

### Applicable Devices

72 73 73A 74 74A 76 77

**Note:** To achieve a 1:1 prescaler assignment for the TMR0 register, assign the prescaler to the Watchdog Timer.

The OPTION register is a readable and writable register which contains various control bits to configure the TMR0/WDT prescaler, the External INT Interrupt, TMR0, and the weak pull-ups on PORTB.

**FIGURE 4-8: OPTION REGISTER (ADDRESS 81h, 181h)**

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
RBP $\bar{U}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit7							bit0

R = Readable bit  
W = Writable bit  
U = Unimplemented bit, read as '0'  
- n = Value at POR reset

bit 7: **RBP $\bar{U}$** : PORTB Pull-up Enable bit  
1 = PORTB pull-ups are disabled  
0 = PORTB pull-ups are enabled by individual port latch values

bit 6: **INTEDG**: Interrupt Edge Select bit  
1 = Interrupt on rising edge of RB0/INT pin  
0 = Interrupt on falling edge of RB0/INT pin

bit 5: **T0CS**: TMR0 Clock Source Select bit  
1 = Transition on RA4/T0CKI pin  
0 = Internal instruction cycle clock (CLKOUT)

bit 4: **T0SE**: TMR0 Source Edge Select bit  
1 = Increment on high-to-low transition on RA4/T0CKI pin  
0 = Increment on low-to-high transition on RA4/T0CKI pin

bit 3: **PSA**: Prescaler Assignment bit  
1 = Prescaler is assigned to the WDT  
0 = Prescaler is assigned to the Timer0 module

bit 2-0: **PS2:PS0**: Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000	1 : 2	1 : 1
001	1 : 4	1 : 2
010	1 : 8	1 : 4
011	1 : 16	1 : 8
100	1 : 32	1 : 16
101	1 : 64	1 : 32
110	1 : 128	1 : 64
111	1 : 256	1 : 128

## 7.3.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control, i.e., it can be changed “on the fly” during program execution.

**Note:** To avoid an unintended device RESET, the following instruction sequence (shown in Example 7-1) must be executed when changing the prescaler assignment from Timer0 to the WDT. This sequence must be followed even if the WDT is disabled.

### EXAMPLE 7-1: CHANGING PRESCALER (TIMER0→WDT)

```

1) BSF STATUS, RP0 ;Bank 1
Lines 2 and 3 do NOT have to 2) MOVLW b'xx0x0xxx' ;Select clock source and prescale value of
be included if the final desired 3) MOVWF OPTION_REG ;other than 1:1
prescale value is other than 1:1. 4) BCF STATUS, RP0 ;Bank 0
If 1:1 is final desired value, then 5) CLRF TMR0 ;Clear TMR0 and prescaler
a temporary prescale value is 6) BSF STATUS, RP1 ;Bank 1
set in lines 2 and 3 and the final 7) MOVLW b'xxxx1xxx' ;Select WDT, do not change prescale value
prescale value will be set in lines 8) MOVWF OPTION_REG ;
10 and 11. 9) CLRWDT ;Clears WDT and prescaler
10) MOVLW b'xxxx1xxx' ;Select new prescale value and WDT
11) MOVWF OPTION_REG ;
12) BCF STATUS, RP0 ;Bank 0

```

To change prescaler from the WDT to the Timer0 module use the sequence shown in Example 7-2.

### EXAMPLE 7-2: CHANGING PRESCALER (WDT→TIMER0)

```

CLRWDT ;Clear WDT and prescaler
BSF STATUS, RP0 ;Bank 1
MOVLW b'xxxx0xxx' ;Select TMR0, new prescale value and
MOVWF OPTION_REG ;clock source
BCF STATUS, RP0 ;Bank 0

```

**TABLE 7-1: REGISTERS ASSOCIATED WITH TIMER0**

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
01h,101h	TMR0	Timer0 module's register								xxxx xxxx	uuuu uuuu
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
81h,181h	OPTION	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	—	PORTA Data Direction Register						--11 1111	--11 1111

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by Timer0.

**TABLE 12-5: BAUD RATES FOR ASYNCHRONOUS MODE (BRGH = 1)**

BAUD RATE (K)	FOSC = 20 MHz			16 MHz			10 MHz			7.16 MHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
9.6	9.615	+0.16	129	9.615	+0.16	103	9.615	+0.16	64	9.520	-0.83	46
19.2	19.230	+0.16	64	19.230	+0.16	51	18.939	-1.36	32	19.454	+1.32	22
38.4	37.878	-1.36	32	38.461	+0.16	25	39.062	+1.7	15	37.286	-2.90	11
57.6	56.818	-1.36	21	58.823	+2.12	16	56.818	-1.36	10	55.930	-2.90	7
115.2	113.636	-1.36	10	111.111	-3.55	8	125	+8.51	4	111.860	-2.90	3
250	250	0	4	250	0	3	NA	-	-	NA	-	-
625	625	0	1	NA	-	-	625	0	0	NA	-	-
1250	1250	0	0	NA	-	-	NA	-	-	NA	-	-

BAUD RATE (K)	FOSC = 5.068 MHz			4 MHz			3.579 MHz			1 MHz			32.768 kHz		
	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)	KBAUD	% ERROR	SPBRG value (decimal)
9.6	9.6	0	32	NA	-	-	9.727	+1.32	22	8.928	-6.99	6	NA	-	-
19.2	18.645	-2.94	16	1.202	+0.17	207	18.643	-2.90	11	20.833	+8.51	2	NA	-	-
38.4	39.6	+3.12	7	2.403	+0.13	103	37.286	-2.90	5	31.25	-18.61	1	NA	-	-
57.6	52.8	-8.33	5	9.615	+0.16	25	55.930	-2.90	3	62.5	+8.51	0	NA	-	-
115.2	105.6	-8.33	2	19.231	+0.16	12	111.860	-2.90	1	NA	-	-	NA	-	-
250	NA	-	-	NA	-	-	223.721	-10.51	0	NA	-	-	NA	-	-
625	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-
1250	NA	-	-	NA	-	-	NA	-	-	NA	-	-	NA	-	-

**Note:** For the PIC16C73/73A/74/74A, the asynchronous high speed mode (BRGH = 1) may experience a high rate of receive errors. It is recommended that BRGH = 0. If you desire a higher baud rate than BRGH = 0 can support, refer to the device errata for additional information, or use the PIC16C76/77.

# PIC16C7X

## 14.4 Power-on Reset (POR), Power-up Timer (PWRT) and Oscillator Start-up Timer (OST), and Brown-out Reset (BOR)

Applicable Devices
72 73 73A 74 74A 76 77

### 14.4.1 POWER-ON RESET (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (in the range of 1.5V - 2.1V). To take advantage of the POR, just tie the MCLR pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for VDD is specified. See Electrical Specifications for details.

When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, ...) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met. Brown-out Reset may be used to meet the startup conditions.

For additional information, refer to Application Note AN607, "Power-up Trouble Shooting."

### 14.4.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms nominal time-out on power-up only, from the POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as the PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip due to VDD, temperature, and process variation. See DC parameters for details.

### 14.4.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-up Timer (OST) provides 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

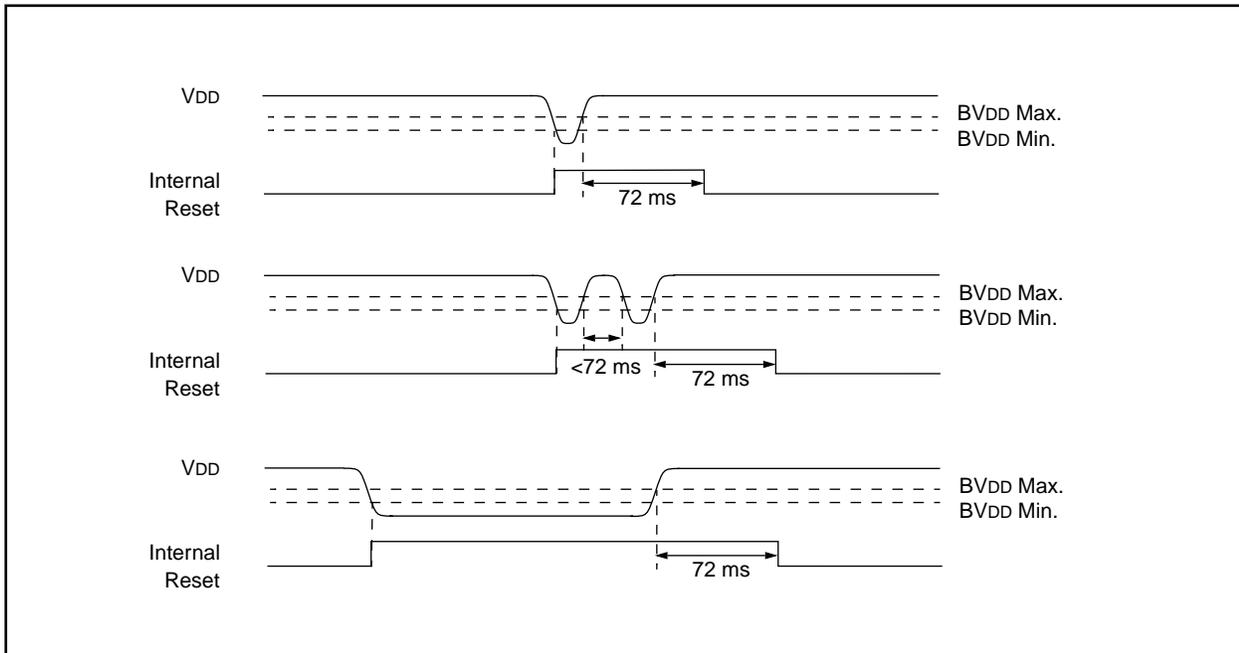
The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

### 14.4.4 BROWN-OUT RESET (BOR)

Applicable Devices
72 73 73A 74 74A 76 77

A configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V (3.8V - 4.2V range) for greater than parameter #35, the brown-out situation will reset the chip. A reset may not occur if VDD falls below 4.0V for less than parameter #35. The chip will remain in Brown-out Reset until VDD rises above BVDD. The Power-up Timer will now be invoked and will keep the chip in RESET an additional 72 ms. If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once VDD rises above BVDD, the Power-up Timer will execute a 72 ms time delay. The Power-up Timer should always be enabled when Brown-out Reset is enabled. Figure 14-9 shows typical brown-out situations.

**FIGURE 14-9: BROWN-OUT SITUATIONS**



## 14.4.5 TIME-OUT SEQUENCE

On power-up the time-out sequence is as follows: First PWRT time-out is invoked after the POR time delay has expired. Then OST is activated. The total time-out will vary based on oscillator configuration and the status of the PWRT. For example, in RC mode with the PWRT disabled, there will be no time-out at all. Figure 14-10, Figure 14-11, and Figure 14-12 depict time-out sequences on power-up.

Since the time-outs occur from the POR pulse, if  $\overline{\text{MCLR}}$  is kept low long enough, the time-outs will expire. Then bringing MCLR high will begin execution immediately (Figure 14-11). This is useful for testing purposes or to synchronize more than one PIC16CXX device operating in parallel.

Table 14-7 shows the reset conditions for some special function registers, while Table 14-8 shows the reset conditions for all the registers.

## 14.4.6 POWER CONTROL/STATUS REGISTER (PCON)

Applicable Devices					
72	73	73A	74	74A	76/77

The Power Control/Status Register, PCON has up to two bits, depending upon the device. Bit0 is not implemented on the PIC16C73 or PIC16C74.

Bit0 is Brown-out Reset Status bit,  $\overline{\text{BOR}}$ . Bit  $\overline{\text{BOR}}$  is unknown on a Power-on Reset. It must then be set by the user and checked on subsequent resets to see if bit  $\overline{\text{BOR}}$  cleared, indicating a BOR occurred. The  $\overline{\text{BOR}}$  bit is a "Don't Care" bit and is not necessarily predictable if the Brown-out Reset circuitry is disabled (by clearing bit BODEN in the Configuration Word).

Bit1 is  $\overline{\text{POR}}$  (Power-on Reset Status bit). It is cleared on a Power-on Reset and unaffected otherwise. The user must set this bit following a Power-on Reset.

**TABLE 14-3: TIME-OUT IN VARIOUS SITUATIONS, PIC16C73/74**

Oscillator Configuration	Power-up		Wake-up from SLEEP
	PWRTE = 1	PWRTE = 0	
XT, HS, LP	72 ms + 1024Tosc	1024Tosc	1024Tosc
RC	72 ms	—	—

**TABLE 14-4: TIME-OUT IN VARIOUS SITUATIONS, PIC16C72/73A/74A/76/77**

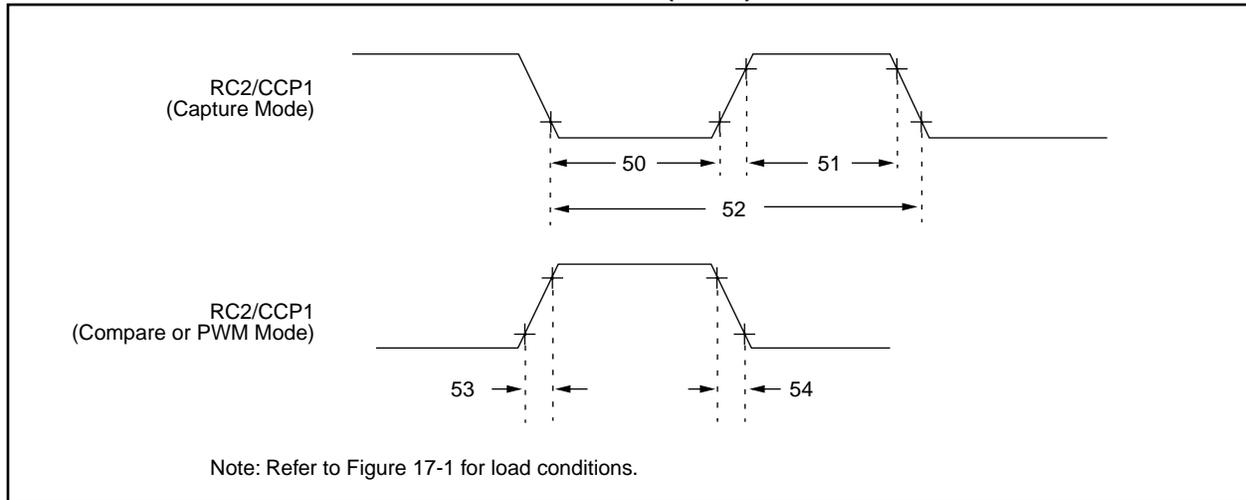
Oscillator Configuration	Power-up		Brown-out	Wake-up from SLEEP
	PWRTE = 0	PWRTE = 1		
XT, HS, LP	72 ms + 1024Tosc	1024Tosc	72 ms + 1024Tosc	1024Tosc
RC	72 ms	—	72 ms	—

**TABLE 14-5: STATUS BITS AND THEIR SIGNIFICANCE, PIC16C73/74**

POR	$\overline{\text{TO}}$	$\overline{\text{PD}}$	
0	1	1	Power-on Reset
0	0	x	Illegal, $\overline{\text{TO}}$ is set on $\overline{\text{POR}}$
0	x	0	Illegal, $\overline{\text{PD}}$ is set on $\overline{\text{POR}}$
1	0	1	WDT Reset
1	0	0	WDT Wake-up
1	u	u	MCLR Reset during normal operation
1	1	0	MCLR Reset during SLEEP or interrupt wake-up from SLEEP

Legend: u = unchanged, x = unknown

**FIGURE 17-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1)**



**TABLE 17-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1)**

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions	
50*	TccL	CCP1 input low time	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler	PIC16C72	10	—	—	ns
				PIC16LC72	20	—	—	ns
51*	TccH	CCP1 input high time	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler	PIC16C72	10	—	—	ns
				PIC16LC72	20	—	—	ns
52*	TccP	CCP1 input period	$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1,4 or 16)	
53*	TccR	CCP1 output rise time	PIC16C72	—	10	25	ns	
			PIC16LC72	—	25	45	ns	
54*	TccF	CCP1 output fall time	PIC16C72	—	10	25	ns	
			PIC16LC72	—	25	45	ns	

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

**TABLE 17-10: A/D CONVERTER CHARACTERISTICS:**  
**PIC16C72-04 (Commercial, Industrial, Extended)**  
**PIC16C72-10 (Commercial, Industrial, Extended)**  
**PIC16C72-20 (Commercial, Industrial, Extended)**  
**PIC16LC72-04 (Commercial, Industrial)**

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions	
A01	NR	Resolution	—	—	8-bits	bit	$V_{REF} = V_{DD} = 5.12V$ , $V_{SS} \leq V_{AIN} \leq V_{REF}$	
A02	EABS	Total Absolute error	—	—	$< \pm 1$	LSb	$V_{REF} = V_{DD} = 5.12V$ , $V_{SS} \leq V_{AIN} \leq V_{REF}$	
A03	EIL	Integral linearity error	—	—	$< \pm 1$	LSb	$V_{REF} = V_{DD} = 5.12V$ , $V_{SS} \leq V_{AIN} \leq V_{REF}$	
A04	EDL	Differential linearity error	—	—	$< \pm 1$	LSb	$V_{REF} = V_{DD} = 5.12V$ , $V_{SS} \leq V_{AIN} \leq V_{REF}$	
A05	EFS	Full scale error	—	—	$< \pm 1$	LSb	$V_{REF} = V_{DD} = 5.12V$ , $V_{SS} \leq V_{AIN} \leq V_{REF}$	
A06	EOFF	Offset error	—	—	$< \pm 1$	LSb	$V_{REF} = V_{DD} = 5.12V$ , $V_{SS} \leq V_{AIN} \leq V_{REF}$	
A10	—	Monotonicity	—	guaranteed	—	—	$V_{SS} \leq V_{AIN} \leq V_{REF}$	
A20	VREF	Reference voltage	3.0V	—	$V_{DD} + 0.3$	V		
A25	VAIN	Analog input voltage	$V_{SS} - 0.3$	—	$V_{REF} + 0.3$	V		
A30	ZAIN	Recommended impedance of analog voltage source	—	—	10.0	k $\Omega$		
A40	IAD	A/D conversion current ( $V_{DD}$ )	PIC16C72	—	180	—	$\mu A$	Average current consumption when A/D is on. (Note 1)
			PIC16LC72	—	90	—	$\mu A$	
A50	IREF	VREF input current (Note 2)	10	—	1000	$\mu A$	During VAIN acquisition. Based on differential of VHOLD to VAIN to charge CHOLD, see Section 13.1.	
			—	—	10	$\mu A$	During A/D Conversion cycle	

\* These parameters are characterized but not tested.

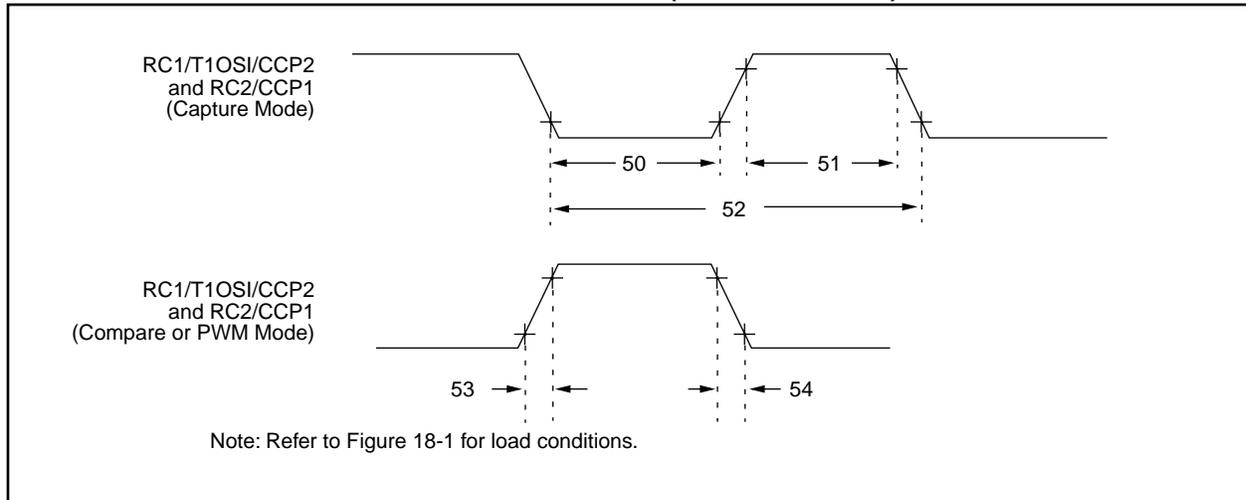
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than minor leakage current.

The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

**FIGURE 18-6: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)**



**TABLE 18-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)**

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions	
50*	TccL	CCP1 and CCP2 input low time	No Prescaler	$0.5T_{CY} + 20$	—	—	ns		
			With Prescaler	PIC16C73/74	10	—	—		ns
				PIC16LC73/74	20	—	—		ns
51*	TccH	CCP1 and CCP2 input high time	No Prescaler	$0.5T_{CY} + 20$	—	—	ns		
			With Prescaler	PIC16C73/74	10	—	—		ns
				PIC16LC73/74	20	—	—		ns
52*	TccP	CCP1 and CCP2 input period		$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1, 4 or 16)	
53*	TccR	CCP1 and CCP2 output fall time	PIC16C73/74	—	10	25	ns		
			PIC16LC73/74	—	25	45	ns		
54*	TccF	CCP1 and CCP2 output fall time	PIC16C73/74	—	10	25	ns		
			PIC16LC73/74	—	25	45	ns		

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

# PIC16C7X

Applicable Devices **72** **73** **73A** **74** **74A** **76** **77**

## 19.4 Timing Parameter Symbolology

The timing parameter symbols have been created following one of the following formats:

- |             |           |  |
|-------------|-----------|--|
| 1. TppS2ppS | 3. TCC:ST | (I <sup>2</sup> C specifications only) |
| 2. TppS     | 4. Ts     | (I <sup>2</sup> C specifications only) |

<b>T</b>			
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

<b>pp</b>			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

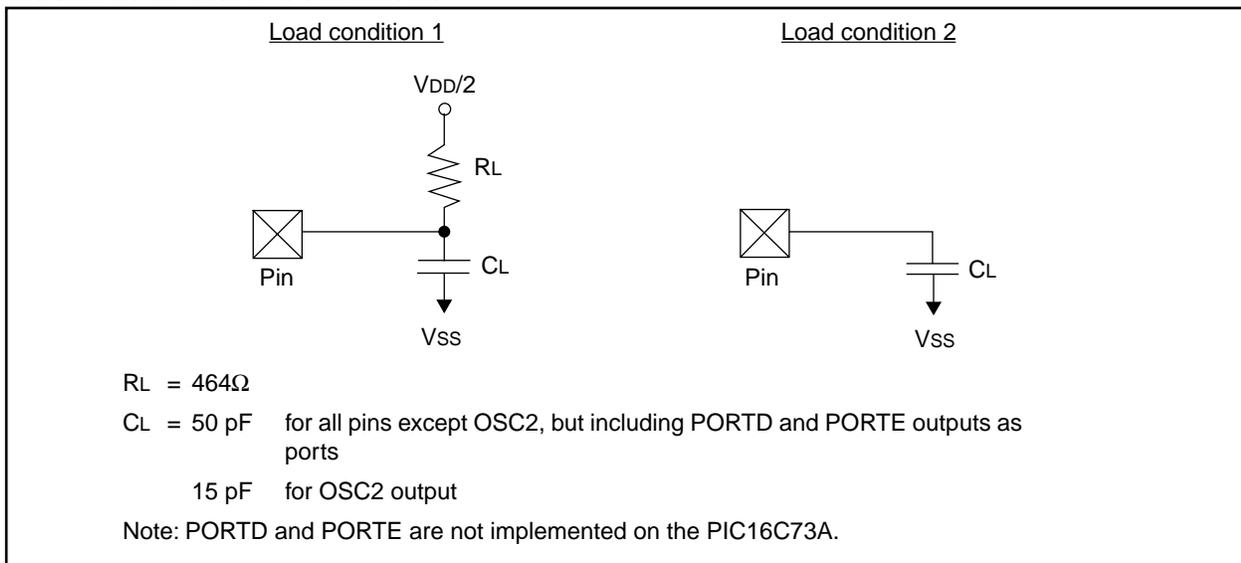
Uppercase letters and their meanings:

<b>S</b>			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance
<b>I<sup>2</sup>C only</b>			
AA	output access	High	High
BUF	Bus free	Low	Low

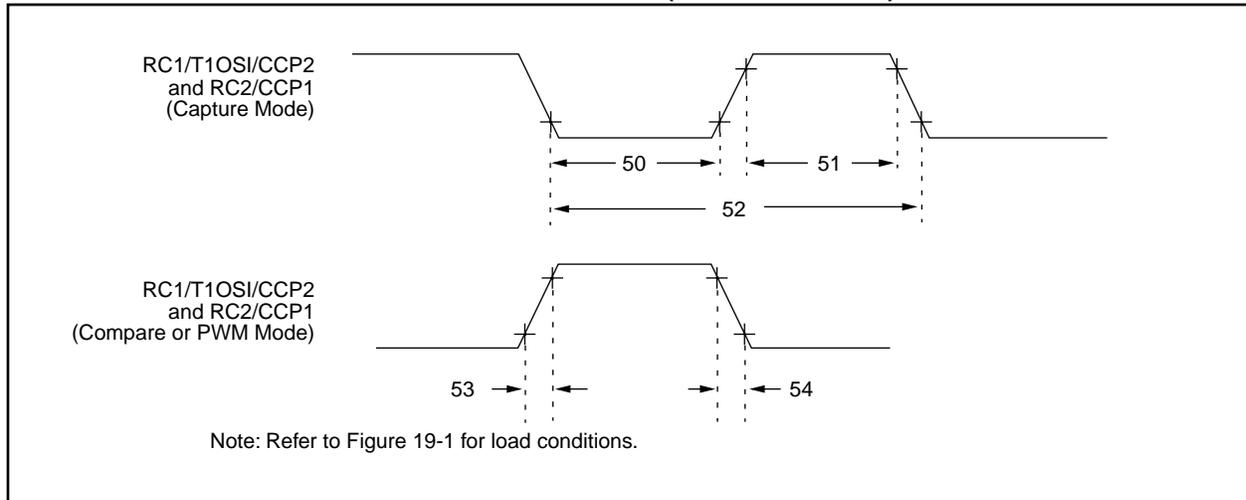
TCC:ST (I<sup>2</sup>C specifications only)

<b>CC</b>			
HD	Hold	SU	Setup
<b>ST</b>			
DAT	DATA input hold	STO	STOP condition
STA	START condition		

**FIGURE 19-1: LOAD CONDITIONS**



**FIGURE 19-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)**



**TABLE 19-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)**

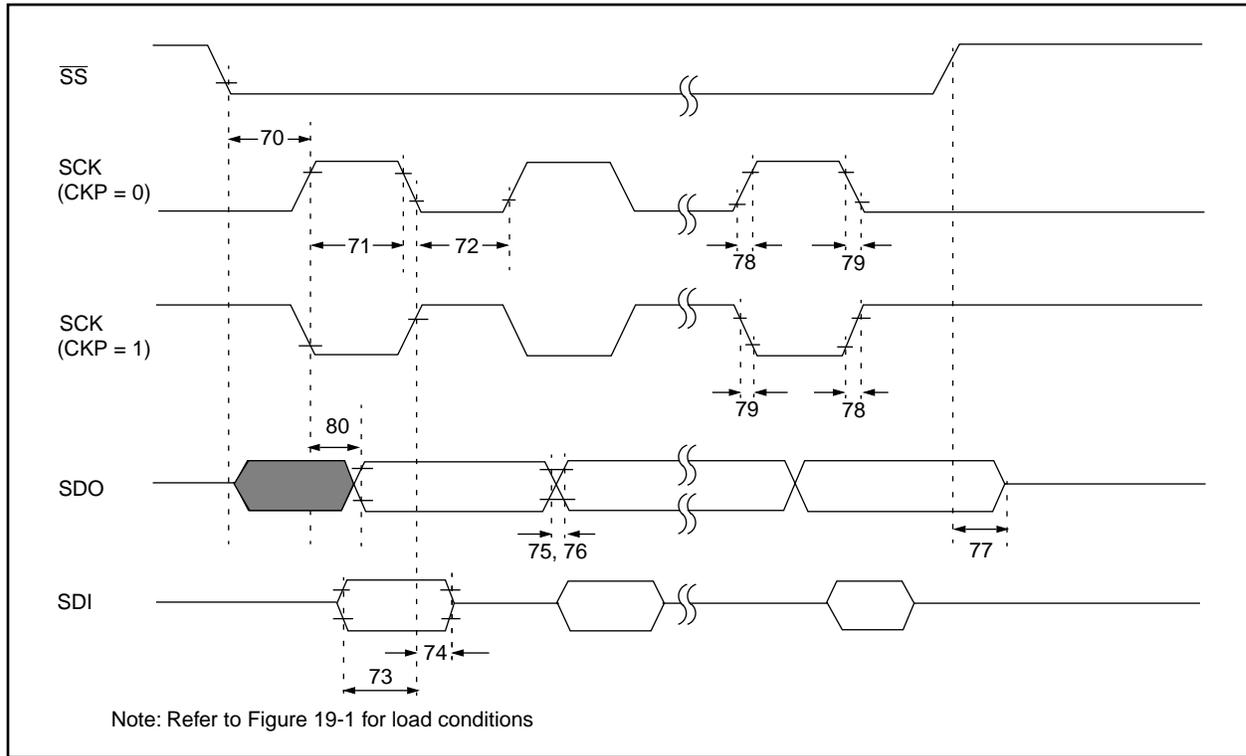
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions	
50*	TccL	CCP1 and CCP2 input low time	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler	PIC16C73A/74A	10	—	—	ns
				PIC16LC73A/74A	20	—	—	ns
51*	TccH	CCP1 and CCP2 input high time	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler	PIC16C73A/74A	10	—	—	ns
				PIC16LC73A/74A	20	—	—	ns
52*	TccP	CCP1 and CCP2 input period	$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1,4 or 16)	
53*	TccR	CCP1 and CCP2 output rise time	PIC16C73A/74A	—	10	25	ns	
			PIC16LC73A/74A	—	25	45	ns	
54*	TccF	CCP1 and CCP2 output fall time	PIC16C73A/74A	—	10	25	ns	
			PIC16LC73A/74A	—	25	45	ns	

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated.

These parameters are for design guidance only and are not tested.

**FIGURE 19-9: SPI MODE TIMING**



**TABLE 19-8: SPI MODE REQUIREMENTS**

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
70	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK $\downarrow$ or SCK $\uparrow$ input	T <sub>CY</sub>	—	—	ns	
71	TscH	SCK input high time (slave mode)	T <sub>CY</sub> + 20	—	—	ns	
72	TscL	SCK input low time (slave mode)	T <sub>CY</sub> + 20	—	—	ns	
73	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	100	—	—	ns	
74	Tsch2diL, TscL2diL	Hold time of SDI data input to SCK edge	100	—	—	ns	
75	TdoR	SDO data output rise time	—	10	25	ns	
76	TdoF	SDO data output fall time	—	10	25	ns	
77	TssH2doZ	$\overline{SS}\uparrow$ to SDO output hi-impedance	10	—	50	ns	
78	TscR	SCK output rise time (master mode)	—	10	25	ns	
79	TscF	SCK output fall time (master mode)	—	10	25	ns	
80	Tsch2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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Applicable Devices 72 73 73A 74 74A 76 77

FIGURE 19-14: A/D CONVERSION TIMING

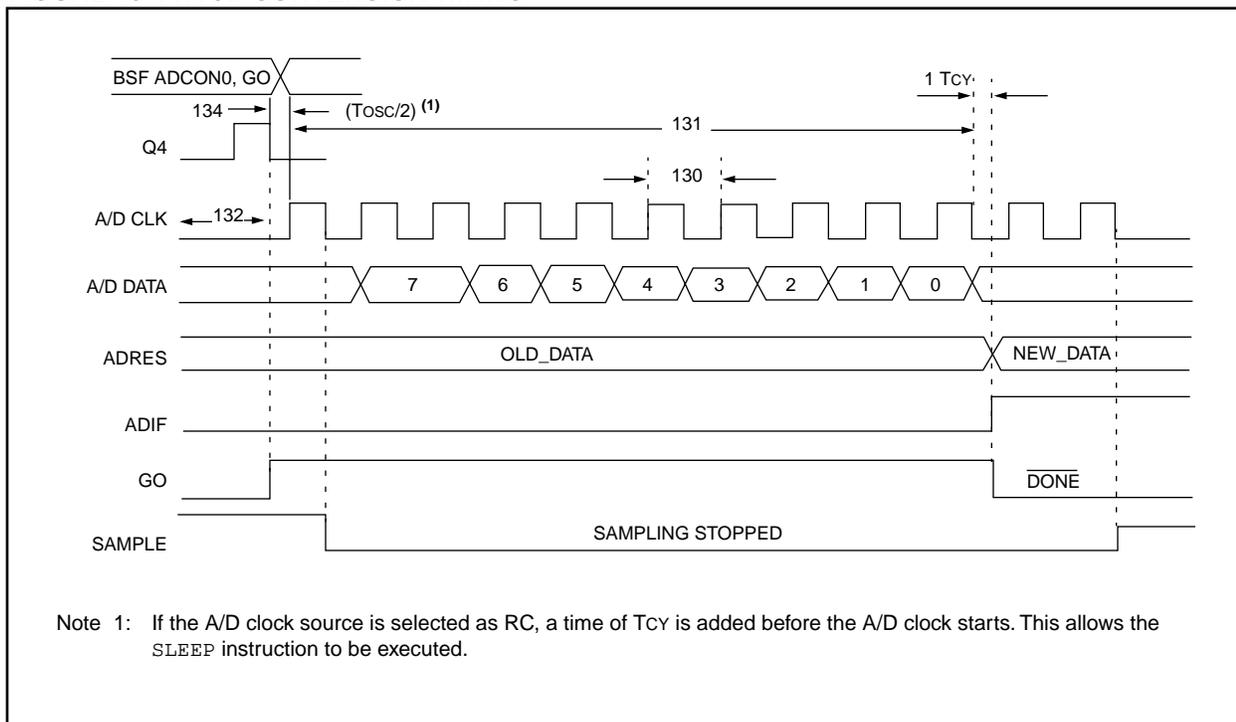


TABLE 19-14: A/D CONVERSION REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
130	TAD	A/D clock period	PIC16C73A/74A	1.6	—	—	μs	TOSC based, VREF ≥ 3.0V
			PIC16LC73A/74A	2.0	—	—	μs	TOSC based, VREF full range
			PIC16C73A/74A	2.0	4.0	6.0	μs	A/D RC Mode
			PIC16LC73A/74A	3.0	6.0	9.0	μs	A/D RC Mode
131	T <sub>CONV</sub>	Conversion time (not including S/H time) (Note 1)	—	9.5	—	TAD		
132	TACQ	Acquisition time	Note 2	20	—	μs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1 LSb (i.e., 20.0 mV @ 5.12V) from the last sampled voltage (as stated on CHOLD).	
			5*	—	—	μs		
134	T <sub>GO</sub>	Q4 to A/D clock start	—	TOSC/2 §	—	—	If the A/D clock source is selected as RC, a time of T <sub>CY</sub> is added before the A/D clock starts. This allows the SLEEP instruction to be executed.	
135	T <sub>SWC</sub>	Switching from convert → sample time	1.5 §	—	—	TAD		

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification ensured by design.

Note 1: ADRES register may be read on the following T<sub>CY</sub> cycle.

2: See Section 13.1 for min conditions.

## 20.0 ELECTRICAL CHARACTERISTICS FOR PIC16C76/77

### Absolute Maximum Ratings †

Ambient temperature under bias .....	-55 to +125°C
Storage temperature .....	-65°C to +150°C
Voltage on any pin with respect to V <sub>SS</sub> (except V <sub>DD</sub> , $\overline{\text{MCLR}}$ , and RA4).....	-0.3V to (V <sub>DD</sub> + 0.3V)
Voltage on V <sub>DD</sub> with respect to V <sub>SS</sub> .....	-0.3 to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to V <sub>SS</sub> (Note 2) .....	0 to +14V
Voltage on RA4 with respect to V <sub>SS</sub> .....	0 to +14V
Total power dissipation (Note 1).....	1.0W
Maximum current out of V <sub>SS</sub> pin .....	300 mA
Maximum current into V <sub>DD</sub> pin .....	250 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>DD</sub> ) .....	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>DD</sub> ).....	±20 mA
Maximum output current sunk by any I/O pin.....	25 mA
Maximum output current sourced by any I/O pin .....	25 mA
Maximum current sunk by PORTA, PORTB, and PORTE (combined) (Note 3).....	200 mA
Maximum current sourced by PORTA, PORTB, and PORTE (combined) (Note 3) .....	200 mA
Maximum current sunk by PORTC and PORTD (combined) (Note 3) .....	200 mA
Maximum current sourced by PORTC and PORTD (combined) (Note 3).....	200 mA

**Note 1:** Power dissipation is calculated as follows:  $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

**Note 2:** Voltage spikes below V<sub>SS</sub> at the  $\overline{\text{MCLR}}$  pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the  $\overline{\text{MCLR}}$  pin rather than pulling this pin directly to V<sub>SS</sub>.

**Note 3:** PORTD and PORTE are not implemented on the PIC16C76.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

# PIC16C7X

Applicable Devices 72 73 73A 74 74A 76 77

**TABLE 20-8: SPI MODE REQUIREMENTS**

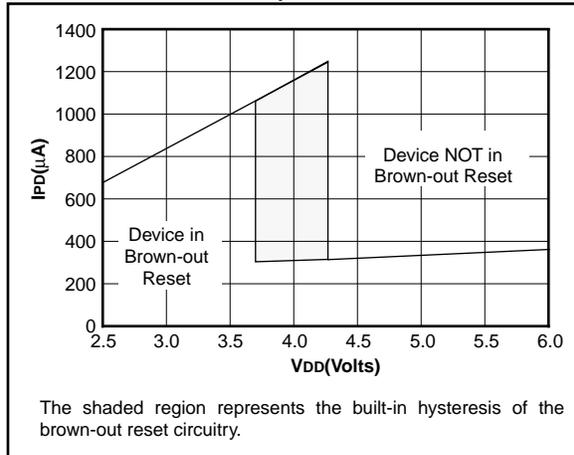
Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK $\downarrow$ or SCK $\uparrow$ input	T <sub>CY</sub>	—	—	ns	
71*	Tsch	SCK input high time (slave mode)	T <sub>CY</sub> + 20	—	—	ns	
72*	TscL	SCK input low time (slave mode)	T <sub>CY</sub> + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	100	—	—	ns	
74*	Tsch2diL, TscL2diL	Hold time of SDI data input to SCK edge	100	—	—	ns	
75*	TdoR	SDO data output rise time	—	10	25	ns	
76*	TdoF	SDO data output fall time	—	10	25	ns	
77*	TssH2doZ	$\overline{SS}\uparrow$ to SDO output hi-impedance	10	—	50	ns	
78*	TscR	SCK output rise time (master mode)	—	10	25	ns	
79*	TscF	SCK output fall time (master mode)	—	10	25	ns	
80*	Tsch2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	
81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge	T <sub>CY</sub>	—	—	ns	
82*	TssL2doV	SDO data output valid after $\overline{SS}\downarrow$ edge	—	—	50	ns	
83*	Tsch2ssH, TscL2ssH	$\overline{SS}\uparrow$ after SCK edge	1.5T <sub>CY</sub> + 40	—	—	ns	

\* These parameters are characterized but not tested.

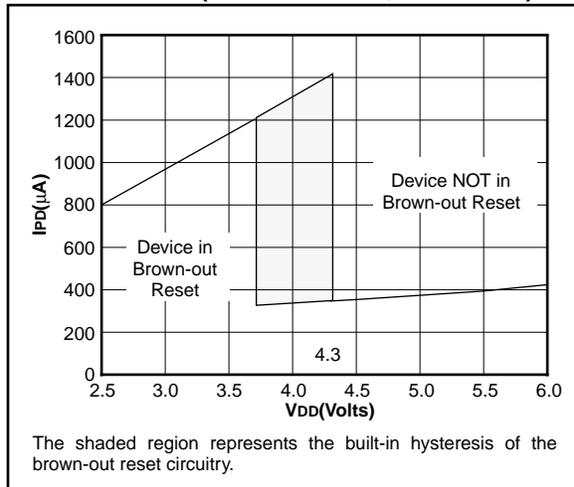
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices 72 73 73A 74 74A 76 77

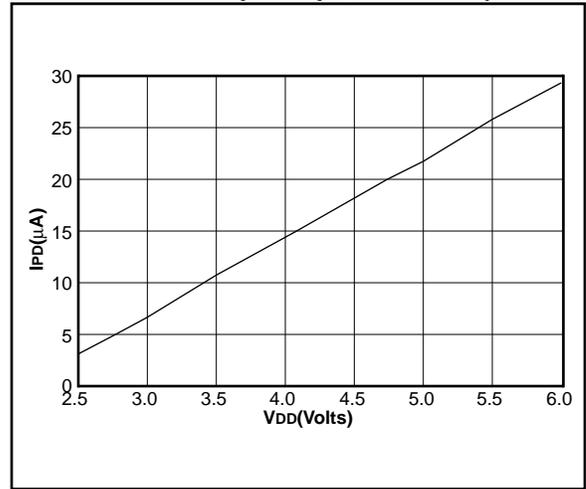
**FIGURE 21-8: TYPICAL  $I_{PD}$  vs.  $V_{DD}$  BROWN-OUT DETECT ENABLED (RC MODE)**



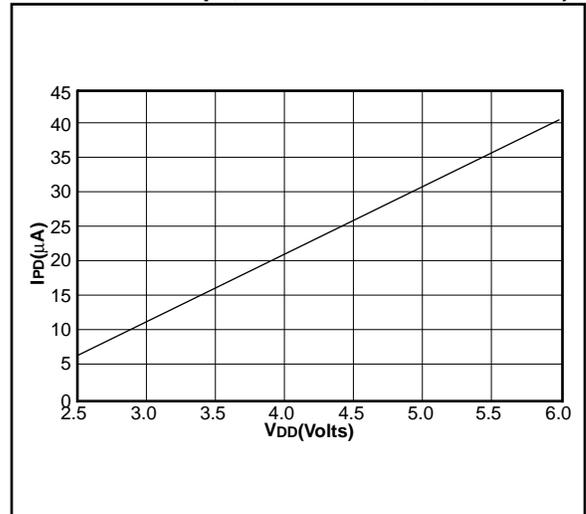
**FIGURE 21-9: MAXIMUM  $I_{PD}$  vs.  $V_{DD}$  BROWN-OUT DETECT ENABLED (85°C TO -40°C, RC MODE)**



**FIGURE 21-10: TYPICAL  $I_{PD}$  vs. TIMER1 ENABLED (32 kHz, RC0/RC1 = 33 pF/33 pF, RC MODE)**



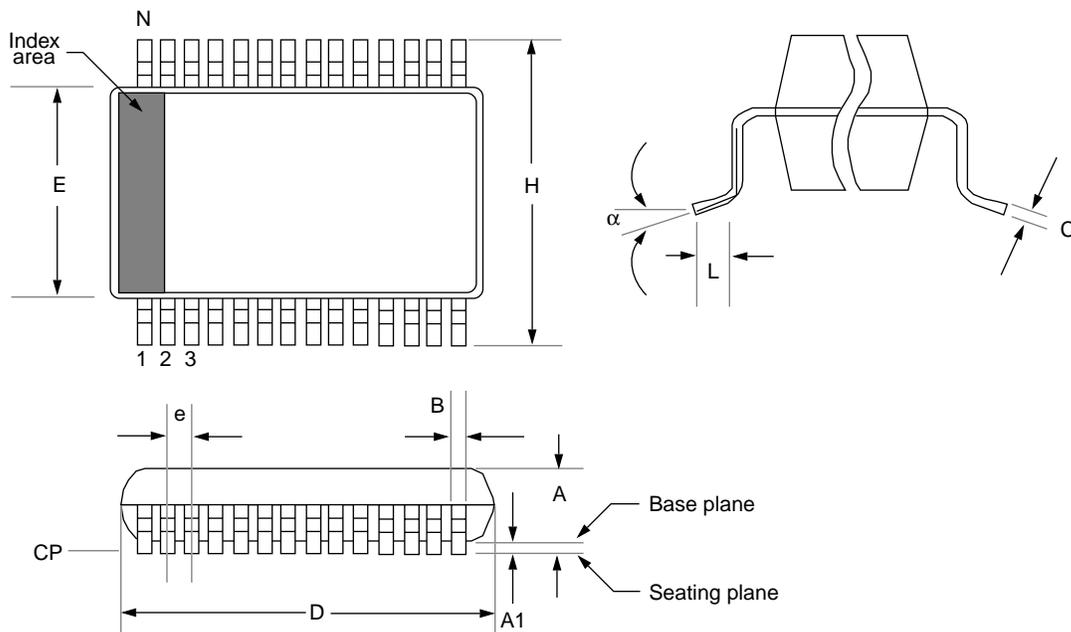
**FIGURE 21-11: MAXIMUM  $I_{PD}$  vs. TIMER1 ENABLED (32 kHz, RC0/RC1 = 33 pF/33 pF, 85°C TO -40°C, RC MODE)**



Data based on matrix samples. See first page of this section for details.

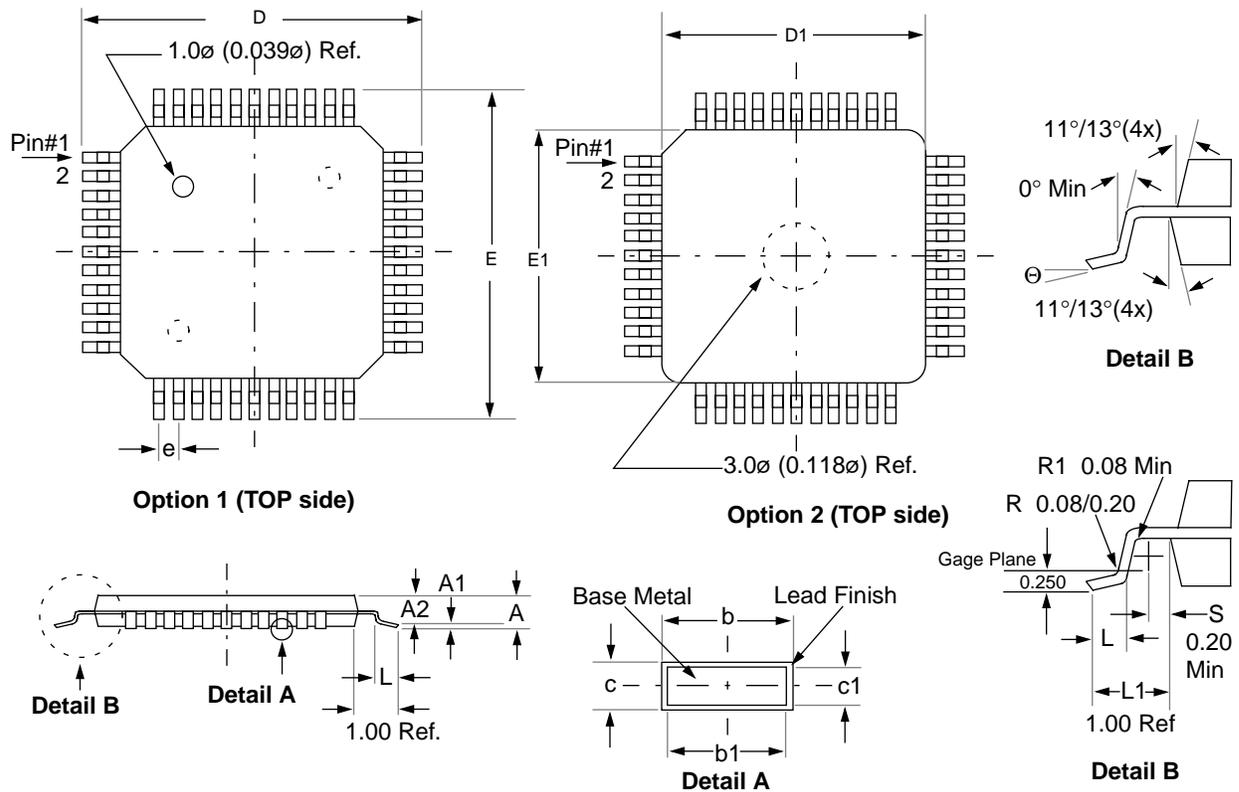
# PIC16C7X

## 22.6 28-Lead Plastic Surface Mount (SSOP - 209 mil Body 5.30 mm) (SS)



Package Group: Plastic SSOP						
Symbol	Millimeters			Inches		
	Min	Max	Notes	Min	Max	Notes
$\alpha$	0°	8°		0°	8°	
A	1.730	1.990		0.068	0.078	
A1	0.050	0.210		0.002	0.008	
B	0.250	0.380		0.010	0.015	
C	0.130	0.220		0.005	0.009	
D	10.070	10.330		0.396	0.407	
E	5.200	5.380		0.205	0.212	
e	0.650	0.650	Reference	0.026	0.026	Reference
H	7.650	7.900		0.301	0.311	
L	0.550	0.950		0.022	0.037	
N	28	28		28	28	
CP	-	0.102		-	0.004	

## 22.9 44-Lead Plastic Surface Mount (TQFP 10x10 mm Body 1.0/0.10 mm Lead Form) (TQ)



Package Group: Plastic TQFP						
Symbol	Millimeters			Inches		
	Min	Max	Notes	Min	Max	Notes
A	1.00	1.20		0.039	0.047	
A1	0.05	0.15		0.002	0.006	
A2	0.95	1.05		0.037	0.041	
D	11.75	12.25		0.463	0.482	
D1	9.90	10.10		0.390	0.398	
E	11.75	12.25		0.463	0.482	
E1	9.90	10.10		0.390	0.398	
L	0.45	0.75		0.018	0.030	
e	0.80 BSC			0.031 BSC		
b	0.30	0.45		0.012	0.018	
b1	0.30	0.40		0.012	0.016	
c	0.09	0.20		0.004	0.008	
c1	0.09	0.16		0.004	0.006	
N	44	44		44	44	
θ	0°	7°		0°	7°	

Note 1: Dimensions D1 and E1 do not include mold protrusion. Allowable mold protrusion is 0.25mm (0.010") per side. D1 and E1 dimensions including mold mismatch.

2: Dimension "b" does not include Dambar protrusion, allowable Dambar protrusion shall be 0.08mm (0.003") max.

3: This outline conforms to JEDEC MS-026.

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